

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2957008

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	AOI HIDAKA	07/09/2014
RECEIVING PARTY DATA		
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	Property Type	Number
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SIGNATURE:	/ak/	
DATE SIGNED:	07/28/2014	
	This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 1		
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Combined Declaration and Assignment for Utility or Design Application

Title of Invention	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	
<p>As the below named inventor, I hereby declare that:</p> <p>This declaration is directed to: <input checked="" type="checkbox"/> The attached application, or</p> <p><input type="checkbox"/> United States application or PCT international application number _____ filed on _____.</p> <p>The above-identified application was made or authorized to be made by me.</p> <p>I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.</p> <p>In consideration of value received, I sell and assign to <u>KABUSHIKI KAISHA TOSHIBA</u>, having a business address at <u>1-1, Shibaura 1-Chome, Minato-Ku, Tokyo, Japan</u>, its successors, assigns or nominees, hereinafter referred to as "Assignee", my entire right, title and interest in and to said invention, and in and to all applications for patent and patents for said invention, in all countries of the world, including all divisions, reissues, continuations, substitutions and extensions thereof and all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of intellectual property, including rights of priority, resulting from the filing of any of said applications.</p> <p>I authorize said Assignee to file and prosecute an application or applications for patent for said invention as the applicant, and I request any official whose duty it is to issue patents, to issue any patent on said invention to said Assignee.</p> <p>I agree that on request and without further consideration, but at the expense of said Assignee, I will communicate to said Assignee or its representatives all facts known to me respecting said invention and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue, or other applications, make all rightful oaths and declarations, and generally do everything possible to aid said Assignee to obtain and enforce proper patent protection for said invention in all countries.</p> <p>I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.</p>		
LEGAL NAME OF INVENTOR		
Aoi HIDAKA	<i>Aoi Hidaka</i>	<i>July 9, 2014</i>
Inventor (printed name)	Signature	Date

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